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a' cancelled.
substantially increased, and the bonding stability is substantially improved when mounted onto the printed circuit board.

IN THE CLAIMS:

Please replace claims 1 and 13 with the following claims:

a2
sub B1
1. A chip electronic component comprising:

a circuit;

an electronic component element having a lower surface and a pair of side surfaces; and

a plurality of external electrodes arranged to extend over the lower surface and at least one of the side surfaces of said electronic component element and electrically connected to the circuit therein; wherein

said each external electrode portion provided on the lower surface of the electronic component element is provided with a narrow portion and a wide portion.

a3
sub B2
13. A mounting structure of a chip electronic component according to claim 1 to be mounted on a printed circuit board via a conductive bond, wherein a bonding portion defined by a conductive bond is located inside of the outer periphery of the chip electronic component as seen from the top of the chip electronic component.